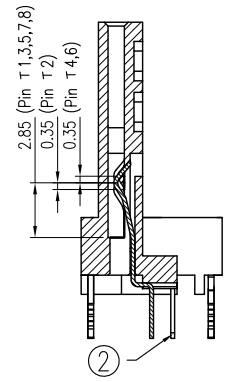
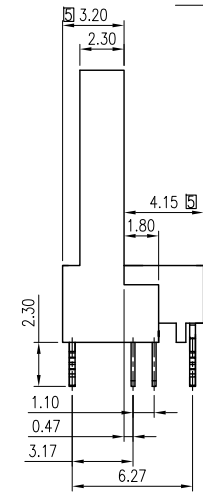
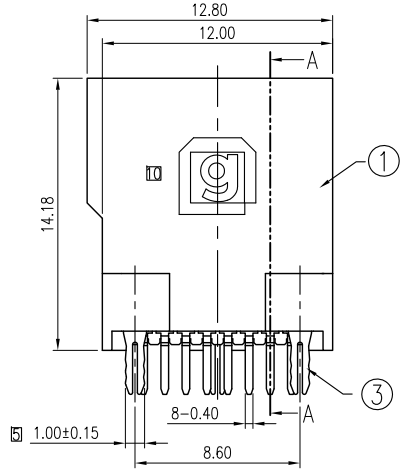
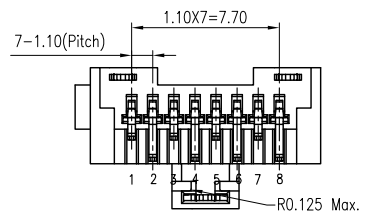
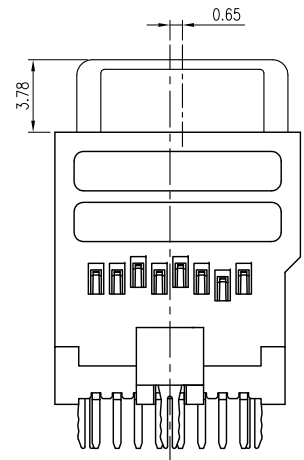


Recommended PCB layout



SECTION A-A



PinT	Description
1	DAT2
2	CD/DAT3
3	CMD
4	V _{DD}
5	CLK
6	V _{SS}
7	DAT0
8	DAT1

10	ADD LOGO	Terry	07/07/10'
9	ADD FILLET	Terry	05/27/10'
8	ADD CHAMFER	Terry	05/25/10'
7	MODIFY DRAWING	Terry	05/14/10'
6	CONTACT PLATING	Terry	05/04/10'
5	MODIFY BOARD LOCK	Terry	04/29/10'
4	MODIFY BOARD LOCK	Terry	04/27/10'
3	MODIFY DRAWING	Terry	04/22/10'
2	ADD NOTES	Terry	03/26/10'
1	ISSUED	Terry	03/17/10'
REV.	ECN NO.	NAME	DATE

TOLERANCE	
LINEAR	ANGLES
X.±0.50	X°.±3°
.X±0.40	.X°±3°
.XX±0.30	.XX°±3°
.XXX±0.15	.XXX°±3°

 <small>Chung-Yang Rd., Tu-Cheng No. 191, Sec. 2 Taipei Hsien, Taiwan</small> A Genesis Electro-Mechanical Company		APPD:	Allen	MAT'L:	
		CHKD:	Daniel	FINISH:	
DRWN:	Terry	Q'TY:			

TITLE:				MICRO SD CARD VERTICAL DIP TYPE			
PART NO.				MSDV-2008-AKX0T01			
DWG NO.				GTi10-25051			
	UNITS	SCALE	SHEET	REV			
	mm	NONE	10F2	10			

PART. NUMBER

MSDV-20 08 - A K X 0 I 01
 ① ② ③ ④ ⑤ ⑥ ⑦

1. CONNECTOR:
MSDV: MICRO SD CARD.
2. TYPE
20: MICRO SD CRAD VERTICAL DIP TYPE
3. POSITIONS
08: 08 POSITION
4. INSULATOR MATERIAL
A: PBT
5. INSULATOR COLOR
K: BLACK
6. CONTACT PLATING
A: GOLD PLATING 12u'
7. SHIELD PLATING
0: NONE SHIELD

Notes:

1. Electrical:
 - a. Voltage Rating: 50VAC (r.m.s)
 - b. Current Rating: 0.5Amperes.
 - c. Insulation Resistance: 1000M ohms min. initial.
 - d. Dielectric Withstand Voltage: AC 500V/1 minute.
 - e. Contact Resistance: 100 m ohms max. initial;
2. Mechanical:
 - a. Material:
 - Contacts: Phosphor Bronze, T=0.2mm.
 - Board Lock: Brass, T=0.3mm.
 - Housing Flammability Rating: PBT, Black, UL94V-0
 - b. Plating:
 - Contacts: Gold plated 12u", Solder tail Tin plated 80u", 50u" nickel underplated overall.
 - Board Lock: Tin plated 80u", 50u" nickel underplated overall.
 - c. Durability: 10,000 Cycles.
 - d. Mating force: 25N Max.
 - Unmating force: 1.5N Min.
 - e. Solderability: More than 90% of solderable area
 - f. Soldering Profile: 260° for 10 seconds without remarkable deterioration.
3. Environmental:
 - a. Operating Temperature: -25°C to +85°C.
Storage Temperature: -40°C to +85°C.
 - b. Steady State Humidity: 90%~95% humidity on 40±2°C for 96hours.
 - c. Thermal Shock: 5 cycles of -55°C to 85°C.
 - d. Vibration Resistance: With dummy card applying DC 100mA,
 Frequency: 10-2000Hz
 Acceleration: 20m/s²
 Sweep rate: 10-2000-10Hz in 5min.
 Duration: 50min.(10 cyc)
 Specimen to be excited along X,Y,and Z axes.(total:150min)
 - e. Impact Resistance: With dummy card applying DC 100mA,
 Shock Waveform: Half sinewave
 Acceleration: 490m/s²
 Impact duration: 11msec.
 9 total impacts delivered 3 each along X,Y, and Z axes. (total:9 impacts)
 - f. After test, contact resistance increase 40m ohms Max.
4. Compliance:
 - a. RoHS Compliance.

PART NO.	MSDV-2008-AKX0T01	SHEET	REVISION
DWG NO.	GTi10-25051	2 OF 2	SEE SHEET 1